CHD8-06

SURFACE MOUNT SILICON HYPERFAST POWER RECTIFIER 8.0 AMP, 600 VOLT



APPLICATIONS:

- Power factor correction
- Motor control



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DESCRIPTION:

The CENTRAL SEMICONDUCTOR CHD8-06 is a high voltage silicon HyperFast power rectifier designed for extremely fast switching applications.

MARKING: FULL PART NUMBER

FEATURES:

- High current capability
- High surge capacity
- HyperFast recovery time (22ns TYP)
- · High voltage

MAXIMUM RATINGS: (T_A=25°C unless otherwise noted)

	SYMBOL		UNITS
Peak Repetitive Reverse Voltage	V_{RRM}	600	V
DC Blocking Voltage	v_R	600	V
RMS Reverse Voltage	V _R (RMS)	420	V
Average Forward Current (T _L =100°C)	lo	8.0	Α
Peak Forward Surge Current, tp=8.3ms	I _{FSM}	70	Α
Operating and Storage Junction Temperature	$T_{J_{I}}T_{stg}$	-65 to +175	°C
Thermal Resistance	Θπ	5.0	°C/W

ELECTRICAL CHARACTERISTICS: (T_A=25°C unless otherwise noted)

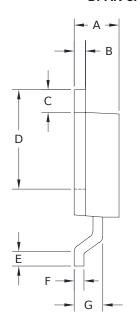
SYMBOL I _R	TEST CONDITIONS VR=600V	TYP	MAX 10	UNITS μΑ
I_{R}	V _R =600V, T _A =150°C		500	μΑ
V_{F}	I _F =8.0A	1.9	2.2	V
CJ	V _R =4.0V, f=1.0MHz	26	35	pF
t _{rr}	I_F =8.0A, V_R =400V, di/dt=200A/ μ s	22	25	ns

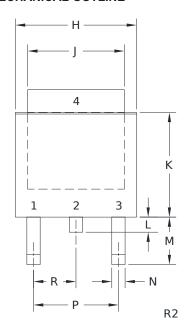
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DPAK CASE - MECHANICAL OUTLINE



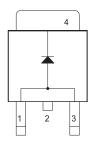


LEAD CODE:

- 1) Anode
- 2) Cathode
- 3) Anode
- 4) Cathode

Pin 2 is common to the tab (4)

MARKING: FULL PART NUMBER



DIMENSIONS							
	INCHES		М	ILLIMETERS			
SYMBOL	MIN	MAX	MIN	MAX			
Α	0.083	0.108	2.10	2.75			
В	0.016	0.035	0.40	0.89			
С	0.035	0.063	0.89	1.60			
D	0.203	0.228	5.15	5.79			
E	0.020	-	0.51	-			
F	0.016	0.024	0.40	0.60			
G	0.061		1.55				
Н	0.248	0.268	6.30	6.81			
J	0.195	0.217	4.95	5.50			
K	0.209	0.245	5.30	6.22			
L	0.033		0.83				
M	0.090	0.115	2.30	2.91			
N	0.012	0.045	0.30	1.14			
Р	0.180		4.60				
R	0.090		2.30				

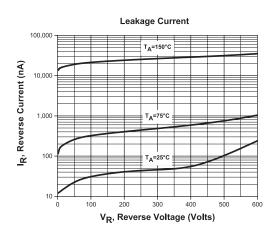
DPAK(REV:R2)

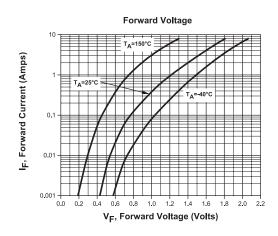
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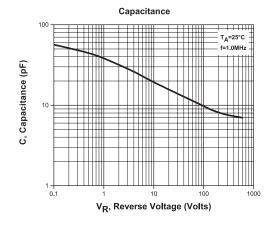
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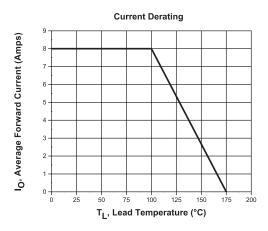


TYPICAL ELECTRICAL CHARACTERISTICS









OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- · Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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